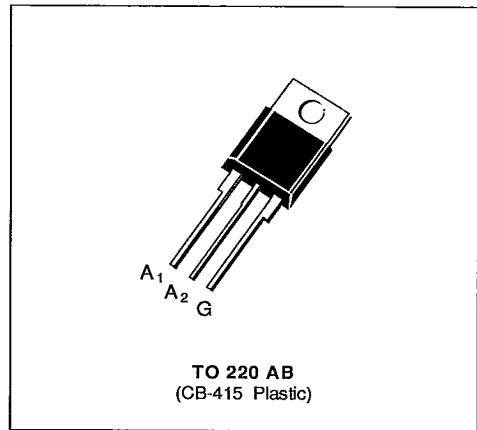


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SNUBBERLESS TRIACS

- $I_{TRMS} = 12 \text{ A}$ at $T_c = 85^\circ\text{C}$.
- $V_{DRM} : 200 \text{ V}$ to 800 V .
- $I_{GT} = 75 \text{ mA}$ (QI-II-III).
- GLASS PASSIVATED CHIP.
- HIGH SURGE CURRENT : $I_{TSM} = 120 \text{ A}$.
- HIGH COMMUTATION CAPABILITY : $(dI/dt)_c > 16 \text{ A/ms}$ without snubber.
- INSULATING VOLTAGE : 2500 VRMS .
- UL RECOGNIZED (E81734).

**DESCRIPTION**

New range suited for applications such as phase control and static switching on inductive or resistive load.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
I_{TRMS}	RMS on-state current (360 ° conduction angle)	12	A
I_{TSM}	Non repetitive surge peak on-state current (T_j initial = 25°C)	$t = 8.3 \text{ ms}$	A
		$t = 10 \text{ ms}$	
$I^2 t$	$I^2 t$ value	72	$\text{A}^2 \text{s}$
dI/dt	Critical rate of rise of on-state current (1)	Repetitive $F = 50 \text{ Hz}$	$\text{A}/\mu\text{s}$
		Non Repetitive	
T_{stg} T_j	Storage and operating junction temperature range	- 40, + 150 - 40, + 125	$^\circ\text{C}$

Symbol	Parameter	BTA 12-					Unit
		200 AW	400 AW	600 AW	700 AW	800 AW	
V_{DRM}	Repetitive peak off-state voltage (2)	± 200	± 400	± 600	± 700	± 800	V

(1) Gate supply : $I_G = 750 \text{ mA}$ - $dI_G/dt = 1 \text{ A}/\mu\text{s}$.(2) $T_j = 125^\circ\text{C}$.

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THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th (j - a)}	Junction to ambient	60	°C/W
R _{th (j - c) DC}	Junction to case for DC	3.3	°C/W
R _{th (j - c) AC}	Junction to case for 360 ° conduction angle (F = 50 Hz)	2.5	°C/W

GATE CHARACTERISTICS (maximum values)

P_{GM} = 40 W (t = 10 μs) P_{G (AV)} = 1 W I_{GM} = 4 A (t = 10 μs) V_{GM} = 16 V (t = 10 μs).

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I _{GT}	T _j = 25 °C	V _D = 12 V	R _L = 33 Ω	I-II-III	2		75	mA
	Pulse duration > 20 μs							
V _{GT}	T _j = 25 °C	V _D = 12 V	R _L = 33 Ω	I-II-III			1.5	V
	Pulse duration > 20 μs							
V _{GD}	T _j = 125 °C	V _D = V _{DRM}	R _L = 3.3 kΩ	I-II-III	0.2			V
	Pulse duration > 20 μs							
I _H *	T _j = 25 °C Gate open	I _T = 100 mA R _L = 140 Ω					75	mA
I _L	T _j = 25 °C	V _D = 12 V	I _G = 500 mA	I-III		75		
	Pulse duration > 20 μs			II		150		mA
V _{TM} *	T _j = 25 °C	I _{TM} = 17 A	t _p = 10 ms				1.6	V
I _{DRM} *	T _j = 25 °C T _j = 125 °C	V _{DRM} rated	Gate open			0.01		
						2		mA
dV/dt *	T _j = 125 °C Gate open	Linear slope up to 0.67 V _{DRM}			750	1000		V/μs
(dI/dt) _c *	T _j = 125 °C	V _{DRM} rated Without snubber			16	32		A/ms
t _{gt}	T _j = 25 °C I _T = 17 A	dI _G /dt = 3.5 A/μs V _D = V _{DRM}	I _G = 500 mA	I-II-III		2		μs

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

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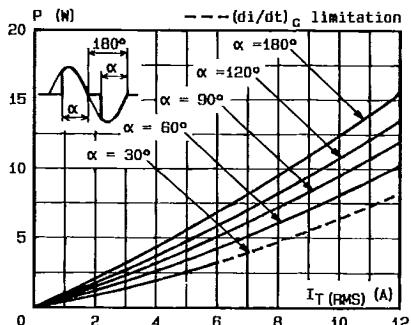
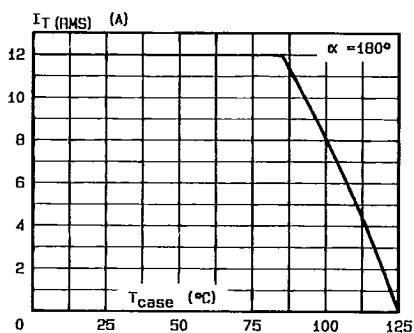
Fig.1 - Maximum mean power dissipation versus RMS on-state current ($f = 60$ Hz).

Fig.3 - RMS on-state current versus case temperature.

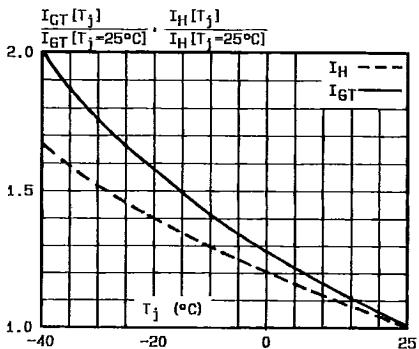


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

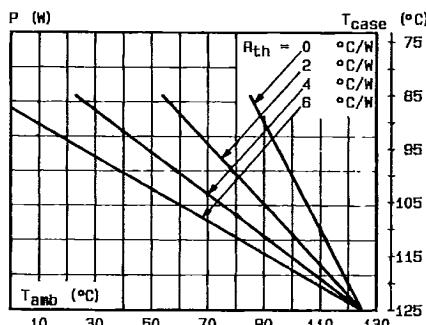
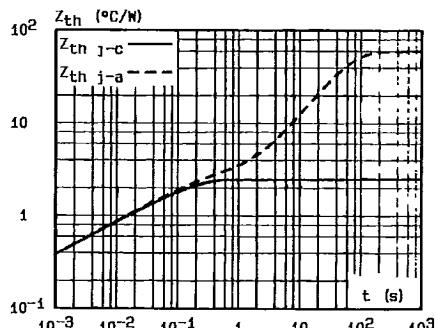
Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

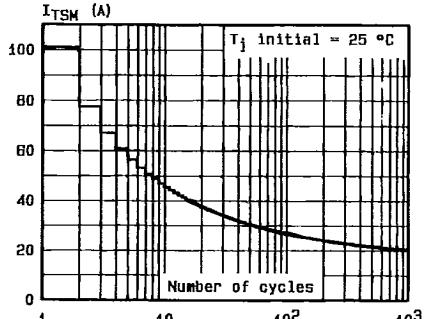
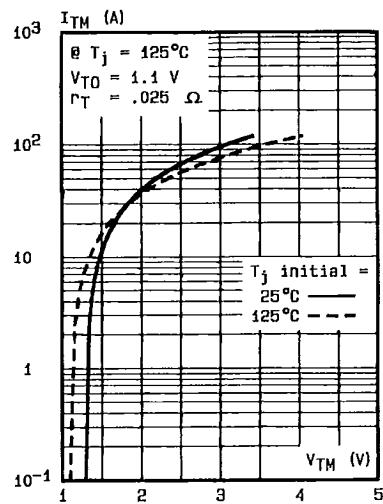
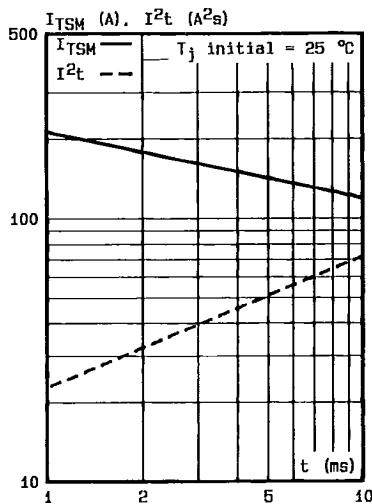
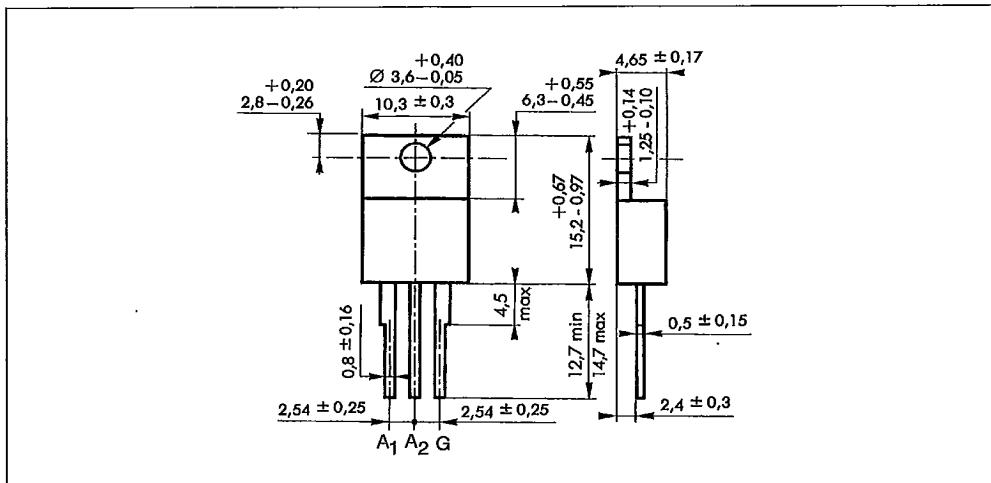


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.



PACKAGE MECHANICAL DATA

TO 220 AB (CB-415) Plastic



Cooling method : by conduction (method C)

Marking : type number

Weight : 2 g